

Title (en)
A process for modelling tiles and slabs

Title (de)
Verfahren zum Modellieren von Fliesen und Platten

Title (fr)
Procédé de modélisation de carreaux et dalles

Publication
EP 1516710 B1 20060628 (EN)

Application
EP 04075870 A 20040318

Priority
IT MO20030255 A 20030919

Abstract (en)
[origin: EP1516710A1] The process comprises the following stages: cutting at least one groove (2) into the upper surface (1a) to a depth therein which is only a part thereof; fixing a thin and flexible temporary support element (3) to the upper surface (1a); making at least one recess (4) which, starting from the lower surface (1b) covers the entire width of the body of the tile (1) in a position corresponding to the groove (2), but not the support element (3); the recess (4) separating the body of the tile (1) into at least two parts, totally separated; nearing the two parts of the tile by bending the thin and flexible temporary support element (3) which keeps the at least two parts of tile (1) (separated by the recess (4)) united, so that the tile (1) is fashioned into the non-flat predetermined conformation. <IMAGE>

IPC 8 full level
B28D 1/30 (2006.01); **B28D 1/00** (2006.01); **B28D 7/04** (2006.01); **E04F 13/14** (2006.01); **E04F 15/02** (2006.01)

CPC (source: EP US)
B28D 1/00 (2013.01 - EP US); **B28D 1/30** (2013.01 - EP US); **B28D 7/04** (2013.01 - EP US); **E04F 13/14** (2013.01 - EP US); **E04F 15/02** (2013.01 - EP US); **E04F 2203/08** (2013.01 - EP)

Cited by
WO2009060492A1; WO2016120748A1

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)
EP 1516710 A1 20050323; **EP 1516710 B1 20060628**; AT E331597 T1 20060715; CA 2463448 A1 20050319; DE 602004001371 D1 20060810; ES 2266980 T3 20070301; IT MO20030255 A1 20050320; MX PA04003659 A 20050328; US 2005072111 A1 20050407

DOCDB simple family (application)
EP 04075870 A 20040318; AT 04075870 T 20040318; CA 2463448 A 20040402; DE 602004001371 T 20040318; ES 04075870 T 20040318; IT MO20030255 A 20030919; MX PA04003659 A 20040419; US 82001004 A 20040408